



PK590 (v1.0) February 1, 2013

100% Material Declaration Data Sheet for 7 Series CSG324 Package

Average Weight: 0.6730 g

Component	Substance Description	CAS Number or Description	Percentage of Component	Use in Product	Component Weight/ Substance Weight (grams)	Component Percent of Total
Silicon Die					0.027377	4.068
	Silicon	7440-21-3	100.00		0.027377	
Die Attach					0.008562	1.272
	Silver	7440-22-4	77.50		0.006636	
	Bismaleimide monomer	Trade Secret	15.00		0.001284	
	Acrylate monomer	Trade Secret	7.50		0.000642	
Mold Compound					0.285271	42.388
	Epoxy Resin	Trade secret	5.00		0.014264	
	Phenol Resin	Trade secret	3.00		0.008558	
	Phenol Novolac	9003-35-4	3.00		0.008558	
	Metal Hydroxide	Trade Secret	3.00		0.008558	
	Carbon black	1333-86-4	0.30		0.000856	
	Silica fused	60676-86-0	70.40		0.200830	
	Silica Dioxide	7631-86-9	15.00		0.042791	
	Silica, crystalline	14808-60-7	0.30		0.000856	
Copper Wire					0.004921	0.731
	Copper	7440-50-8	98.20		0.004832	
	Palladium	7440-05-3	1.80		0.000089	
Solder Ball					0.114185	16.966
	Tin	7440-31-5	96.50		0.110188	
	Silver	7440-22-4	3.00		0.003426	
	Copper	7440-50-8	0.50		0.000571	

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Substrate					0.232687	34.574
	Copper	7440-50-8	15.70		0.036532	
	Nickel	7440-02-0	6.80		0.015823	
	Gold	7440-57-5	0.81		0.001885	
	Glass fiber	65997-17-3	20.14		0.046863	
	Non halogen fire retardant	NA	0.01		0.000023	
	BT core	105391-33-1 25722-66-1 9003-36-5 21645-51-2 7440-50-8	46.11		0.107292	
Solder mask	147-14-8 7727-43-7 7631-86-9 14807-96-6 112-15-2 34590-94-8 103429-90-9 64742-94-5 25551-13-7	10.43		0.024269		

Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
02/01/2013	1.0	Xilinx Initial Release

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